EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	6849	29/831,832,840,841,844,846,851, 854.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:43
S2	1747	156/64,356,357,358.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:43
S3	1955	228/175,180.22,227.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:43
S4	34921	mount$3 with (electronic adj component)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:07
S5	638	S1 and S4	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:44
S6	1648	melt$3 near ((conduct$3 adj bond$3) or solder) with component	USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:06
S7	67	S3 and S6	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:45
S8	0	S2 and S6	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:45
S9	3	S5 and S7	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:47
S10	96	S1 and S6	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:47
S11	38	S4 and S10	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:56
S12	4	(("5878942") or ("6133637")).PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/06/30 16:56
S13	7	("4620215" | "4764804" | "5108950" | "5148266" | "5376825" | "5523628" | "5864178").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 16:56
S14	5	("4604644" | "5121190" | "5371404" | "5385869" | "5629566").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 16:58
S15	19	("5864178").URPN.	USPAT	OR	ON	2005/06/30 16:59

S16	7	("4620215" | "4764804" | "5108950" | "5148266" | "5376825" | "5523628" | "5864178").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:01
S17	7	("4620215" | "4764804" | "5108950" | "5148266" | "5376825" | "5523628" | "5864178").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:05
S18	20	TSUYOSHI-YAMAMOTO.in. or MITSUO-SUEHIRO.in. or HIROSHI-YAMADA.in.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/01 09:04
S19	0	S4 and S18	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:06
S20	0	S6 and S18	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:06
S21	3	melt$3 near ((conduct$3 adj bond$3) or solder) with (before near mount$3 with component)	USPAT; JPO; DERWENT	OR	ON	2005/06/30 17:07
S22	2	JP-01072590-$.did.	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:02
S23	3	(melt$3 or heat$3) near (solder adj paste) with (terminal adj pad)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:07
S24	2	(melt$3 or heat$3) same (solder adj paste) same (terminal adj pad) same (before or (prior adj to))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:08
S25	28	melt$3 near ((conduct$3 adj bond$3) or solder) with before with mount$3	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:10
S26	9	(US-6209196-$ or US-5722160-$ or US-5629566-$ or US-6133637-$).did. or (JP-06164124-$ or JP-04269893-$ or JP-01072590-$ or JP-57188833-$).did. or (JP-2003224351-$).did.	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:51
S27	1	S26 and ((low adj meting$3) or (high$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
S28	303	(thermoplastic near (high$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:54
S29	201	(thermoplastic adj resin) near (high$2 adj melting)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:54
S30	0	(anisotrophic) near (high$2 adj melting)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:55

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S31	0	(anisotropic) near (high$2 adj melting)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:55
S32	16	(anisotropic) near (melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:56
S33	1284	(solder) near (low adj melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
S34	0	S32 and S33	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:56
S35	0	(solder) near (low adj melting adj point) near degree	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
S36	0	(solder) near (low$2 adj melting adj point) near degree	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
S37	1747	(solder) near (low$2 adj melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
S38	0	solder near ((low adj meting$3) and (high$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:00
S39	0	solder near ((low$2 adj meting$3) and (high$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:01
S40	0	S29 and S37	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:06
S41	6474	different with (melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:06
S42	64	S41 and (mount$3 with (electronic adj component))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
S43	1974	174/259,260.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:50
S44	227	S43 and (mount$3 with (electronic adj component))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
S45	1	S41 and S44	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51

S46	14	S43 and (mount$3 with (electronic adj component) with support)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
S47	230	YAMAMOTO-TSUYOSHI.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:04
S48	31	SUEHIRO-MITSUO.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:05
S49	2593	YAMADA-HIROSHI.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:05
S50	2849	S47 or S48 or S49	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:05
S51	10	melt$3 near (solder or gold) near (bond$3 or terminal) near pad	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:10
S52	138	melt$3 near (solder or gold) near pad	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:11
S53	3035	S50 and8	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:11
S54	1	S50 and S52	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:12
S55	25	(electric$2 near component) with (temporary) with ((circuit near board) or wafer or substrate)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:50
S56	1890	encapsulat$3 with (bond$3 near pad)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:51
S57	0	S52 and S56	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:51

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S58	0	S50 and (mount$3 near component$1) and (melt$3 near bond$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:52
S59	15	S50 and (mount$3 near component$1)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:53
S60	6	S59 and melt$3	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:55
S61	18060	melt$3 with (temporary or support)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:56
S62	1179	melt$3 near (temporary or support)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:57
S63	0	S62 and (mount$3 near electric$2 near component$1)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:57
S64	0	S62 and (mount$3 same (electric$2 near component$1))	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:57
S65	20632	(mount$3 same (electric$2 near component$1))	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:57
S66	0	S62 and S65	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:57
S67	57	S61 and S65	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 09:58
S68	36	S67 and @ad<"20010919"	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 10:07
S69	1896	encapsulat$3 same (electric$2 near component$1)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 10:06

S70	56	encapsulat$3 same (electric$2 near component$1) same melt$3	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 10:06
S71	35	S70 and @ad<"20010919"	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 10:07
S72	11826	resin$4 with melt$3 with (contact$3 or bond$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:51
S73	347	resin$4 near melt$3 near (contact$3 or bond$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:49
S74	0	resin$4 near melt$3 near (contact$3 or bond$3) near pad$1	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:49
S75	0	resin$4 near melt$3 near (contact$3 or bond$3) near component	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:49
S76	0	resin$4 near melt$3 near (contact$3 or bond$3) near encapsulat$3	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:49
S77	46	S73 and encapsulat$3	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:49
S78	4317	resin$4 with melt$3 with heat$3 with (contact$3 or bond$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:51
S79	42	resin$4 with melt$3 with heat$3 with (contact$3 or bond$3) with pad$1	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/01 12:51
S80	7139	438/103,106,108,112,118,119,127. ccls.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/02 13:44
S81	191	S80 and standoff	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/02 13:44

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S82	72	S81 and melt$3 and chip and contact$3	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/02 13:46
S83	38	S82 and @ad<"20010901"	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/02/02 13:52
S84	2	("6444560").PN.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	OFF	2006/02/02 13:56
S85	2	("5633535").PN.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	OFF	2006/02/02 13:57
S86	2	("5633535").PN.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	OFF	2006/02/02 13:58
S87	37	("5633535").URPN.	USPAT	OR	ON	2006/02/02 13:58
S88	7	("4927697" | "4967950" | "5056215" | "5130779" | "5154341" | "5218234" | "5448114").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:03
S89	2	("4666545" | "4755249").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/02 14:04
S90	12	("4927697").URPN.	USPAT	OR	ON	2006/02/02 14:04
S91	1	("6981317").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/04/25 10:03
S92	1	("6981317").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	OFF	2006/05/16 07:52
S93	31489	(bond$3 or contact$3 or attach$3) with melt$3 with (resin$4 or solder or adhesive)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 07:53
S94	1153	(bond$3 or contact$3 or attach$3) near melt$3 near (resin$4 or solder or adhesive)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 07:53

S95	10	(bond$3 or contact$3 or attach$3) near melt$3 near (resin$4 or solder or adhesive) near (substrate or (circuit near board))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:07
S96	1566	438/118.ccls.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:12
S97	2847	self near bond$3	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:08
S98	2	S96 and S97	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:07
S99	245	S93 and S97	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:07
S10 0	4	S94 and S97	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:07
S10 1	191	self near bond$3 near (resin or adhesive)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:12
S10 2	1	(self near bond$3 near (resin or adhesive)) same (mov$3 near down)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:11
S10 3	15	(self near bond$3 near (resin or adhesive)) same ((mov$3 near down) or lower$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:13
S10 4	86679	bond$3 near (resin or adhesive)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:12
S10 5	283	S96 and S104	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:12
S10 6	205	S105 and ((mov$3 near down) or lower$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:12
S10 7	8219	(bond$3 near (resin or adhesive)) same ((mov$3 near down) or lower$3)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:13
S10 8	113	(bond$3 near (resin or adhesive)) same (((mov$3 near down) or lower$3) near (chip or substrate or (electrical near component)))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:14
S10 9	67	(bond$3 near (resin or adhesive)) with (((mov$3 near down) or lower$3) near (chip or substrate or (electrical near component)))	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/05/16 08:14